



# **Intel<sup>®</sup> Server Board SE7210TP1-E Memory List Test Report Summary**

*Revision 34.0  
October 2006*

<b>Revision History</b>		
<b>Date</b>	<b>Rev</b>	<b>Modifications</b>
Jan/04	.5	Pre-release.
Feb/04	1.0	Release document. Added Micron 128MB & 256MB parts. Added Infineon 256MB, 512MB & 1G parts.
Feb/04	1.1	Added Infineon 128MB & 1G parts. Added Micron 256MB & 512MB parts. Added Samsung 512MB part.
Mar/04	2.0	Added TRS 256MB and 512MB parts. Added Smart and Avant 1GB parts. (In shaded area)
Mar/04	3.0	Added ATP and Dataram 256MB parts. Added ATP, Dataram, Ventura and Smart 512MB parts. Added Avant 1GB parts. (In shaded area)
Apr/04	4.0	Added Buffalo 256MB, 512MB, and 1GB parts. Added Legend and ATP 256MB parts. Added Ventura 512MB parts. (In shaded area)
May/04	5.0	Added Viking 256MB and 512MB parts. Added Avant, Legend, Micron, Smart, and Legacy 512MB parts. Added ATP & Infineon 1GB parts. (In shaded area)
Jun/04	6.0	Added Avant 256MB part. Added Simple, Transcend and Legend 512MB parts. Added TRS and Legend 1GB parts. (In shaded area)
Jun/04	7.0	Added Dane-Elec & Buffalo 256MB parts. Added Infineon, Legend & ATP 512MB parts. Added Buffalo, ATP 1GB parts.
July/04	8.0	Added Dane-elec, Buffalo, Legend, and Smart 256MB parts. Added Dane-Elec, Buffalo, Apacer, Legend, Wintec, and Smart parts. Added Smart, Buffalo, Dataram, and Legend 1GB parts. (In shaded area)
Aug/04	9.0	Added Buffalo and Avant 256MB parts. Added Apacer and Buffalo 512MB parts. Added Apacer 1GB parts. (In shaded area)
Aug/04	10.0	Added Legend and TRS 256MB parts. Added Buffalo 512MB parts. Added Apacer, Buffalo and TRS 1GB parts. (In shaded area)
Sep/04	11.0	Added Apacer 256MB and 512MB parts. (In shaded area)
Oct/04	12.0	Added Legend and Ventura 512MB parts. (In shaded area)
Oct/04	13.0	Added Buffalo 512MB parts. Micron 1G part. (In shaded area)
Dec/04	14.0	Added Simple 256MB and 512MB parts. Added TRS 512MB parts. (In shaded area)
Dec/04	15.0	Added Viking 512MB and Buffalo 1GB parts. (In shaded area)
Jan/05	16.0	Added ATP 512MB parts. (In shaded area)
Jan/05	17.0	Added Buffalo 256MB and Infineon 512MB parts. (In shaded area)
Feb/05	18.0	Added Samsung and Infineon 512MB parts. Added ATP and Samsung 1GB parts. (In shaded area)
Feb/05	19.0	Added Dataram 256MB and 512MB parts. (In shaded area)
Mar/05	20.0	Added Buffalo and Dataram 512MB parts. (In shaded area)
Mar/05	21.0	Added note on Lead free modules (these modules are now in bold text). Added Simple 256MB parts. Added Buffalo 512MB parts. (In shaded area)
Apr/05	22.0	Added Samsung 128MB and 256MB parts. Added Infineon 256MB part. (In shaded area)
Apr/05	23.0	Added Buffalo 256MB parts. Added Legacy 1GB parts. (In shaded area)
May/05	24.0	Added Buffalo 1GB parts. (In shaded area)
Jun/05	25.0	Added Simple 256MB parts. Added Centon 512MB parts. Added Wintec 1GB parts. (In shaded area)
Aug/05	26.0	Added Dataram and Simple 512MB parts. Added TRS 1GB parts. (In shaded area)
Aug/05	27.0	Added Avant 1GB parts. (In shaded area)
Nov/05	28.0	Added Avant and Buffalo 1GB parts. (In shaded area)
Dec/05	29.0	Added Legend 256MB and 512MB parts. Added Buffalo 1GB part. (In shaded area)
Mar/06	30.0	Added Buffalo 512MB and 1GB parts. (In shaded area)
May/06	31.0	Infineon name change to Qimonda effective May 1 <sup>st</sup> , 2006. Added ATP 512MB part. (In shaded area)
June/06	32.0	Added Buffalo and Avant Technology 512MB and 1G parts. (In shaded area)
July/06	33.0	Added Buffalo and Smart 1GB parts. (In shaded area)
Oct/06	34.0	Added Dataram 1GB part. (In shaded area)

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The Intel® Server Board SE7210TP1-E may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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***Please Note:*** DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each bank on the memory module is NOT recommended.

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## Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7210TP1-E. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)<sup>1</sup>. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel's Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft\* Windows\* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

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<sup>1</sup> CMTL is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Office: (949) 716-8690  
Fax (949) 716-8691

Computer Memory Test Lab (CMTL)  
24 Hammond Suite F  
Irvine, CA 92618  
<http://www.cmtlabs.com/>

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## Qualified Memory for the Intel® Server Board SE7210TP1-E

The memory module on the server board SE7210TP1-E has 4 DIMM sockets, which can hold up to 4 GB of Unbuffered ECC and non-ECC DDR266, DDR333 or DDR400 memory using four 72-bit DIMM modules. The following memory features are supported:

- DDR266, DDR333 and DDR400 Unbuffered ECC and non-ECC compatible 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMMs with capacity of 128MB, 256 MB, 512 MB, 1G. Other DRAM sizes may function correctly but will not be validated.
- Minimum configuration is 128MB using one 128MB DIMM.

Below is a chart that lists the current supported memory types:

<b>DDR266, DDR333, and DDR400 Unbuffered SDRAM Module Matrix</b>					
<b>DIMM Capacity</b>	<b>DIMM Organization</b>	<b>SDRAM Density</b>	<b>SDRAM Organization</b>	<b># SDRAM Devices/rows/Banks</b>	<b># Address bits rows/Banks/column</b>
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11

Memory features are detailed in *the Intel® Server Board SE7210TP1-E Technical Product Specification* available on-line at <http://support.intel.com/support/motherboards/server/SE7210TP1-E>

The following table lists DIMM devices known to be compatible with the Intel Server Board SE7210TP1-E. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

**Caution:** Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

**Note:** This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

***This list is subject to change without notice.***

## Server Board SE7210TP1-E

### Unbuffered, ECC, DDR266 DIMM Modules 128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72D16000GU-7-A	HYB250D128800AT-7A	~ Qimonda (Infineon)		2/23/04	2	Yes	(16Mx8)*9	

### Unbuffered, ECC, DDR333 DIMM Modules 128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M381L1713ETM-CB3	K4H280838E-TCB3	Samsung		3/15/04	2.5	Yes	(16Mx8)*9	

### Unbuffered, ECC, DDR400 DIMM Modules 128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT5VDDT1672AG-40BC3	MT46V16M16-5B C	Micron		1/27/04	3	Yes	(16Mx8)*9	
Samsung	M381L1713ETM-CCC	K4H280838E-TCCC	Samsung		5/24/04	3	Yes	(16Mx8)*9	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

## *Server Board SE7210TP1-E*

### *Unbuffered, Non-ECC, DDR266 DIMM Modules 128MB Sizes (16Mx72)*

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>EOL</b>

### *Unbuffered, Non-ECC, DDR333 DIMM Modules 128MB Sizes (16Mx72)*

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>EOL</b>

### *Unbuffered, Non-ECC, DDR400 DIMM Modules 128MB Sizes (16Mx72)*

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>EOL</b>

*Modules shaded in blue are low profile.*

*Modules in bold text do not contain Lead.*

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

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## Server Board SE7210TP1-E

### Unbuffered, ECC, DDR266 DIMM Modules 256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M381L3223ETM-CA2	K4H560838E-TCA2	Samsung		1/19/04	2	Yes	(32Mx8)*9	
~ Qimonda (Infineon)	HYS72D32000GU-7-A	HYB25D256800AT-7A	~ Qimonda (Infineon)		1/27/04	2	Yes	(32Mx8)*9	
Micron	MT9VDDT3272AG-265B1	MT46V32M8-75 B	Micron		2/9/04	2.5	Yes	(32Mx8)*9	
Micron	MT9VDDT3272AG-265C4	MT46V32M8-75 C	Micron		2/23/04	2.5	Yes	(32Mx8)*9	

### Unbuffered, ECC, DDR333 DIMM Modules 256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT9VDDT3272AG-335C4	MT46V32M8-6TC	Micron		1/12/04	2.5	Yes	(32Mx8)*9	
~ Qimonda (Infineon)	HYS72D32300HU-6-C	HYB25D256800CE-6	~ Qimonda (Infineon)		2/9/04	2.5	Yes	(32Mx8)*9	
+ATP Electronics	AG32L72T8SQB3S	K4H560838F-TCB3 rev F	Samsung	SG184T08 L1	3/12/04	2.5	Yes	(32Mx8)*9	
+Legend	L3272DC7-DR1HDC9B	HY5DU56822BT-D43 rev B	Hyundai	DR720818 C1 rev 1	3/17/04	3	Yes	(32Mx8)*9	
+ATP Electronics	AG32L72T8SQC4S	K4H560838F-TCCC rev F	Samsung	SG184T08 L1 rev 1	3/19/04	3	Yes	(32Mx8)*9	
+Avant Technology	AVM7232U39C5333K4-A	MT46V32M8TG(P)-6T rev G	Micron	50-1402-01-B rev B	5/25/04	2.5	Yes	(32Mx8)*9	
+Buffalo	DD333-ES256/SF	K4H560838F-TCB3 rev F	Samsung	UE0832-AA	6/28/04	2.5	Yes	(32Mx8)*9	
Samsung	M381L3223ETM-CB3	K4H560838E-TCB3	Samsung		5/24/04	2.5	Yes	(32Mx8)*9	

### Unbuffered, ECC, DDR400 DIMM Modules 256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72D32300GU-5-B	HYB25D256800BT-5B	~ Qimonda (Infineon)		1/12/04	3	Yes	(32Mx8)*9	
Samsung	M381L3223ETM-CCC	K4H560838E-TCCC	Samsung		1/18/04	3	Yes	(32Mx8)*9	
Micron	MT18VDDT3272AG-40BB5	MT46V16M8-5B	Micron		2/23/04	3	Yes	(16Mx8)*18	
+TRS	TRS20172	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	M0534LA1 rev 1	2/20/04	3	Yes	(32Mx8)*9	
+Dataram	DTM63671B	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	40570 rev A	3/8/04	3	Yes	(32Mx8)*9	
+Viking	VI4CU327228DTPL2	V58C2256804SAT5 B rev B	Mosel Vitelic	0000981A	5/6/04	3	Yes	(32Mx8)*9	
+Legend	L3272DC7-MA6HDC9C	HY5DU56822CT-D43 rev C	Hyundai	BDMA83A 6 rev 6	6/23/04	3	Yes	(32Mx8)*9	
+Smart Modular Technologies	SM3272DDR2N1-IC	HYB25D256800CE-5 rev C	~ Qimonda (Infineon)	184-30-3	6/17/04	3	Yes	(32Mx8)*9	

**Unbuffered, ECC, DDR400 DIMM Modules  
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD4333-ES256/SF	K4H560838F-TCCC rev F	Samsung	UE0832-AA	6/30/04	3	Yes	(32Mx8)*9	
+Buffalo	DD4333-ES256/IB	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	UE0832-AA	7/1/04	3	Yes	(32Mx8)*9	
+Legend	L3272DC7-MA6HDC9D	HY5DU56822DT-D43 rev D	Hyundai	BDMA83A 6 rev 6	8/25/04	3	Yes	(32Mx8)*9	
+TRS	TRS20182	HYB25D256800CE-5 rev C	~ Qimonda (Infineon)	M0534LA1 rev 1	8/12/04	3	Yes	(32Mx8)*9	
+Apacer	77.10638.335	HYB25D256800CE-5 rev C	~ Qimonda (Infineon)	48.16118.0 15 rev 5	9/7/04	3	Yes	(32Mx8)*9	
SimpleTech	ST72C8F32-A05A	V58C2256804SAT5 rev A	Mosel Vitec	1077 rev B	10/21/04	3	Yes	(32Mx8)*9	
+Dataram	DTM63671C	HYB25D256800CE-5 rev C	~ Qimonda (Infineon)	40570 rev A	2/10/05	3	Yes	(32Mx8)*9	
SimpleTech	ST72C8F32ML-A05A	HYB25D256800CT-5 rev C	~ Qimonda (Infineon)	B6U806R	3/8/05	3	Yes	(32Mx8)*9	
~ Qimonda (Infineon)	HYS72D32300HU-5-C	HYB25D256800CE-5C	~ Qimonda (Infineon)		5/24/04	3	Yes	(32Mx8)*9	
+Buffalo	DD4333-ES256/MG	MT46V32M8TG-5B rev G	Micron	UE0832-AA	3/30/05	3	Yes	(32Mx8)*9	
SimpleTech	ST72C8F32-A05A	V58C2256804SCT5 B rev C	Mosel Vitec	1077 rev B	6/2/05	3	Yes	(32Mx8)*9	

*Modules shaded in blue are low profile.*

*Modules in bold text do not contain Lead.*

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

## Server Board SE7210TP1-E

### Unbuffered, Non-ECC, DDR266 DIMM Modules 256MB Sizes (32Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

### Unbuffered, Non-ECC, DDR333 DIMM Modules 256MB Sizes (32Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333-S256/SF	K4H560838F-TCB3 rev F	Samsung	UE0832-AA	4/13/04	2.5	Yes	(32Mx8)*8	
+Dane-Elec	OD1D333-064325I-1MG	MT46V32M8TG(P)-6T rev G	Micron	DR5128-33	6/21/04	2.5	Yes	(32Mx8)*8	
+Legend	L3264DC6-BU1HDC5D	HY5DU56822DT-J rev D	Hyundai	B6U808 rev 1	8/24/04	2.5	Yes	(32Mx8)*8	

### Unbuffered, Non-ECC, DDR400 DIMM Modules 256MB Sizes (32Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L3264DC7-BU1HDC9C	HY5DU56822CT-D43 rev C	Hyundai	B6U808 rev 1	4/9/04	3	Yes	(32Mx8)*8	
+Buffalo	DD4333-S256/SF	K4H560838F-TCCC rev F	Samsung	UE0832-AA	6/3/04	3	Yes	(32Mx8)*8	
+Dane-Elec	OD1D400-064323I-1MG	MT46V32M8TG(P)-5B rev G	Micron	DR5128-33	6/9/04	3	Yes	(32Mx8)*8	
+Buffalo	DD4333-S256/IC	HYB25D256800CE-5 rev C	~ Qimonda (Infineon)	UE0832-AA rev C	7/6/04	3	Yes	(32Mx8)*8	
+Avant Technology	AVM6432U39C3 400K5-MVA	V58C2256804SAT5B rev A	Mosel Vitelic	B6U808 1.1 rev 1	7/19/04	3	Yes	(32Mx8)*8	
+Legend	L3264DC7-BU1HDC9D	HY5DU56822DT-D43 rev D	Hyundai	B6U808 rev 1	8/23/04	3	Yes	(32Mx8)*8	
+Buffalo	DD4333-S256/MG	MT46V32M8TG(P)-5B rev G	Micron	UE0832-AA	1/14/05	3	Yes	(32Mx8)*8	
+Legend	L3264DC7-U61HDKSC	HY5DU121622CTP-D43 rev C	Hynix	B6U602 rev 1	11/30/05	3	Yes	(32Mx16)*4	

*Modules shaded in blue are low profile.*

*Modules in bold text do not contain Lead.*

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

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**Server Board SE7210TP1-E**  
**Unbuffered, ECC, DDR266 DIMM Modules**  
**512MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT18VDDT6472AG-265C4	MT64v32M8-75C	Micron		2/24/04	2.5	Yes	(32Mx8)*18	
Samsung	M381L6423DTL-CA2	K4H560838D-TCA2	Samsung			2	Yes	(32Mx8)*18	
+Legend	L6472DC5-DR1HDC5A	HY5DU56822AT-H rev A	Hyundai	DR720818C rev 1	6/9/04	2.5	Yes	(32Mx8)*18	

**Unbuffered, ECC, DDR333 DIMM Modules**  
**512MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72D64320HU-6-C	HYB25D256800CE-6C	~ Qimonda (Infineon)		2/2/04	2.5	Yes	(32Mx8)*18	
Micron	MT18VDDT6472AG-335C4	MT46V32M8-6TC	Micron		2/23/04	2.5	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQB3S	K4H560838F-TCB3 rev F	Samsung	SG184T08L1	3/12/04	2.5	Yes	(32Mx8)*18	
+Ventura Technology Group	D52XVK29SV	K4H560838E-TCB3 rev E	Samsung	V215	3/10/04	2.5	Yes	(32Mx8)*18	
+Avant Technology	AVM7264U39C5333K4-A	MT46V32M8TG(P)-6T rev G	Micron	50-1402-01-B rev B	4/29/04	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/SE	K4H560838E-TCB3 rev E	Samsung	UE0532-AA	6/25/04	2.5	Yes	(32Mx8)*18	
+Apacer	77.10735.334	HYB25D256800CE-6 rev C	~ Qimonda (Infineon)	48.16118.014 rev 4	7/1/04	2.5	Yes	(32Mx8)*18	
+Apacer	77.10735.464	K4H560838F.TC B3 rev F	Samsung	48.16118.014 rev 4	7/2/04	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/SF	K4H560838F-TCB3 rev F	Samsung	UE0532-AA	8/20/04	2.5	Yes	(32Mx8)*18	
Micron	MT18VDDT6472AG-40BC4	MT46V32M8-5B C	Micron		1/24/04	3	Yes	(32Mx8)*18	
+TRS	TRS20173	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	M0524LA1 rev 1	2/18/04	3	Yes	(32Mx8)*18	
+Smart Modular Technologies	SM6472DDR2N1	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	L-DIM-184-31-1	3/3/04	3	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQC4S	K4H560838F-TCCC rev F	Samsung	SG184T08L1	3/8/04	3	Yes	(32Mx8)*18	
+Dataram	DTM63672B	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	40570 rev A	3/4/04	3	Yes	(32Mx8)*18	
+Legend	L6472DC7-DR1HDC9B	HY5DU56822BT-D43 rev B	Hyundai	DR720818C rev 1	4/19/04	3	Yes	(32Mx8)*18	
+Smart Modular Technologies	SM6472DDR2N1-SF	K4H560838F-TCCC rev F	Samsung	M381L3313DTM	4/23/04	3	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQB3C	HYB25D256800BT-6 rev B	~ Qimonda (Infineon)	SG184T08L1	12/22/04	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/MG	MT46V32M8-6TG rev G	Micron	UE0532-AA	2/25/05	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/MG	MT46V32M8-6TG rev G	Micron	UE0532-AA	2/25/05	2.5	Yes	32M x 8	

**Unbuffered, ECC, DDR400 DIMM Modules  
512MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT9VDDT6472AG-40BC1	MT46V64M8-5BC	Micron		1/18/04	3	Yes	(64Mx8)*9	
+Viking	VI4CU647228DTPL2	V58C2256804S AT5B rev B	Mosel Vitelic	000981A	5/4/04	3	Yes	(32Mx8)*18	
Micron	MT9VDDT6472AG-40BD1	MT46V64M8-5B D	Micron		5/3/04	3	Yes	(64Mx8)*9	
Micron	MT18VDDT6472AG-40BG4	MT46V32M8-5B G	Micron		5/6/04	3	Yes	(32Mx8)*18	
SimpleTech	ST72C8F64-A05AS	K4H560838E-TCCC rev E	Samsung	1077 rev B	5/17/04	3	Yes	(32Mx8)*18	
Transcend Information	TS64MLD72V4F3 (HU)	V58C2256804S AT5B	Mosel Vitelic	09-1835	5/24/04	3	Yes	(32Mx8)*18	
~ Qimonda (Infineon)	HYS72D64320HU-5-C	HYB25D256800 CE-5C	~ Qimonda (Infineon)		6/14/04	3	Yes	(32Mx8)*18	
+Legend	L6472DC7-MA6HDC9C	HY5DU56822CT-D43 rev C	Hyundai	BDMA83A 6 rev 6	6/21/04	3	Yes	(32Mx8)*18	
+Buffalo	DD4333-E512/IB	HYB25D256800 BT-5 rev B	~ Qimonda (Infineon)	UE0532-AA	6/29/04	3	Yes	(32Mx8)*18	
+Buffalo	DD4333-E512/SF	K4H560838F-TCCC rev F	Samsung	UE0532-AA	6/29/04	3	Yes	(32Mx8)*18	
+Wintec Industries	3C745684	K4H510838B-TCCC rev B	Samsung	ZK512M68 J-A	6/23/04	3	Yes	(64Mx8)*9	
+Smart Modular Technologies	SM6472DDR2N1-IC	HYB25D256800 CE-5 rev C	~ Qimonda (Infineon)	L-DIM-184-31-1	6/11/04	3	Yes	(32Mx8)*18	
+Apacer	77.10738.334	HYB25D256800 CE-5 rev C	~ Qimonda (Infineon)	48.16118.0 94 rev 4	9/1/04	3	Yes	(32Mx8)*18	
+Ventura Technology Group	D52AVQ40SV	K4H560838F-TCCC rev F	Samsung	DR1GB8-33	9/10/04	3	Yes	(32Mx8)*18	
+Buffalo	DD4333-E512/MG	MT46V32M8TG(P)-5B rev G	Micron	UE0532-AA	10/7/04	3	Yes	(32Mx8)*18	
SimpleTech	ST72C8F64-A05AS	V58C2256804S AT5 rev A	Mosel Vitelic	1077 rev B	10/12/04	3	Yes	(32Mx8)*18	
+TRS	TRS20183	HYB25D256800 CE-5 rev C	~ Qimonda (Infineon)	M0524LA1 rev 1	10/14/04	3	Yes	(32Mx8)*18	
+Viking	VI4CU646428DTPL3	K4H560838F-TCCC rev F	Samsung	0000981A	12/14/04	3	Yes	(32Mx8)*18	
~ Qimonda (Infineon)	HYS72D64300HU-5-B	HYB25D512800 BE-5B	~ Qimonda (Infineon)		1/14/05	3	Yes	(64Mx8)*9	
Samsung	M381L6423ETM-CCC	K4H560838E-TCCC	Samsung		1/21/05	3	Yes	(32Mx8)*18	
~ Qimonda (Infineon)	HYS72D64320GU-5-C	HYB25D256800 CT-5C	~ Qimonda (Infineon)		2/1/05	3	Yes	(32Mx8)*18	
+Dataram	DTM63672C	HYB25D256800 CE-5 rev C	~ Qimonda (Infineon)	40570 rev A	2/1/05	3	Yes	(32Mx8)*18	
+Centon Electronics	TOP-004	V58C2256804S CI5 rev C	Mosel Vitelic	LE18DDT1 848 rev A	5/26/05	3	Yes	(32Mx8)*18	
+Dataram	DTM63715A	HYB25D512800 CE-5 rev C	~ Qimonda (Infineon)	40024A rev A	7/5/05	3	Yes	(64Mx8)*9	
SimpleTech	ST72C8F64-A05AS	V58C2256804S CT5B rev C	Mosel Vitelic	01077 rev B	7/7/05	3	Yes	(32Mx8)*18	
<b>Avant Technology</b>	<b>AVM7264U52C3400K4-MTF</b>	<b>MT46V64M8TG-5B F rev F</b>	<b>Micron</b>	<b>50-1402-01-B rev B</b>	<b>05/08/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*9</b>	

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*Modules in bold text do not contain Lead.*

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

## Server Board SE7210TP1-E

### Unbuffered, Non-ECC, DDR266 DIMM Modules 512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

### Unbuffered, Non-ECC, DDR333 DIMM Modules 512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Ventura Technology Group	D51XVK29SV	K4H560838E-TCB3 rev E	Samsung	V215	3/19/04	2.5	Y	(32Mx8)*16	
+Buffalo	DD333-512/SF	K4H560838F-TCB3 rev F	Samsung	UE0532-AA	4/13/04	2.5	Y	(32Mx8)*16	
+Dane-Elec	OD1D333-064645I-1MG	MT46V32M8TG(P)-6T rev G	Micron	DR1GB8-33	6/24/04	2.5	Yes	(32Mx8)*16	

### Unbuffered, Non-ECC, DDR400 DIMM Modules 512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legacy Electronics Inc.	88S5HDL0-1UDG	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	LE18DDT1848 rev A	4/19/04	3	Yes	(32Mx8)*16	
+Legend	L6464DC7-DE6HDC5B	HY5DU56822BT-D43 rev B	Hyundai	DE640816 A rev 6	5/10/04	3	Yes	(32Mx8)*16	
+Legend	L6464DC7-BU1HDC9C	HY5DU56822CT-D43 rev C	Hyundai	B6U808 rev 1	5/27/04	3	Yes	(32Mx8)*16	
+ATP Electronics	AG64L64T8SQ C4S	K4H560838F-TCCC rev F	Samsung	SG184T08L1 rev 1	6/7/04	3	Yes	(32Mx8)*16	
+Dane-Elec	OD1D400-064643I-1MG	MT46V32M8TG(P)-5B rev G	Micron	DR1GB8-33	6/17/04	3	Yes	(32Mx8)*16	
+Buffalo	DD4333-512/SF	K4H560838F-TCCC rev F	Samsung	UE0532-AA	6/15/04	3	Yes	(32Mx8)*16	
+Buffalo	DD4333-512/IC	HYB25D256800CE-5 rev C	~ Qimonda (Infineon)	UE0532-AA	7/8/04	3	Yes	(32Mx8)*16	
+Legend	L6464DC7-BU1HDC9D	HY5DU56822DT-D43 rev D	Hyundai	B6U808 rev 1	9/21/04	3	Yes	(32Mx8)*16	
+Buffalo	DD4333-512/MG	MT46V32M8TG(P)-5B rev G	Micron	UE0532-AA	9/29/04	3	Yes	(32Mx8)*16	
<b>+Legend</b>	<b>L6464DC7-BU1HDC9C</b>	<b>HY5DU12822CTP-D43 rev C</b>	<b>Hynix</b>	<b>B6U808 rev 1</b>	<b>12/6/05</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*9</b>	
+Dataram	DTM63668B	HYB25D256800BT-5 rev B	~ Qimonda (Infineon)	40570 rev A	2/18/05	3	Yes	(32Mx8)*16	
<b>+Buffalo</b>	<b>DD4333-S512/MDJ</b>	<b>MT46V64M8P-5B rev D</b>	<b>Micron</b>	<b>UE0832-AAna</b>	<b>3/3/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*9</b>	
<b>Buffalo</b>	<b>DD4333-S512MFJ</b>	<b>MT46V64M8P-5B rev F</b>	<b>Micron</b>	<b>UE0832-AAna</b>	<b>04/29/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*9</b>	

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## Server Board SE7210TP1-E

### Unbuffered, ECC, DDR266 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
~ Qimonda (Infineon)	HYS72D128020GU-7-A	HYB25D512800AT-7A	~ Qimonda (Infineon)		2/9/04	2	Yes	(64Mx8)*18	

### Unbuffered, ECC, DDR333 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Avant Technology	AVM7228U52C5333 K4-A	MT46V64M8TG-5B rev C	Micron	50-1402-01-B rev B	2/27/04	2.5	Yes	(64Mx8)*18	
+ATP Electronics	AG28L72T8SHB3S	K4H510838B-TCB3 rev B	Samsung	SG184T08L 1 rev 1	5/6/04	2.5	Yes	(64Mx8)*18	
~ Qimonda (Infineon)	HYS72D128320HU-6-B	HYB25D512800BE-6B	~ Qimonda (Infineon)		4/28/04	2.5	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872DDR6H1	HYB25D512800AT-6 rev A	~ Qimonda (Infineon)	L-DIM-184-31-1	6/21/04	2.5	Yes	(64Mx8)*18	
+Apacer	77.11135.464	K4H510838B-TCB3 rev B	Samsung	48.16118.01 4 rev 4	7/6/04	2.5	Yes	(64Mx8)*18	
+Apacer	76.01220.182	HYB25D512800BE-5 rev B	~ Qimonda (Infineon)	48.16118.01 4 rev 4	8/11/04	2.5	Yes	(64Mx8)*18	
+Buffalo	DD333-1G/MD	MT46V64M8TG(P)-6T rev D	Micron	UE0532-AA	12/10/04	2.5	Yes	(64Mx8)*18	
+Legacy Electronics Inc.	89S6KDL0-1NDG	HYB25D512800BE-6 rev B	~ Qimonda (Infineon)	LE18DDT18 48 rev A	4/11/05	2.5	Yes	(64Mx8)*18	
<b>ATP Electronics</b>	<b>AG64L72T8SHB3S</b>	<b>K4H510838C-UCCC rev C</b>	<b>Samsung</b>	<b>SG184T08L 1 na</b>	<b>04/17/06</b>	<b>2.5</b>	<b>Yes</b>		

### Unbuffered, ECC, DDR400 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT18VDDT12872AG-40BC1	MT46V64M8-5BC	Micron		1/18/04	3	Yes	(64Mx8)*18	
~ Qimonda (Infineon)	HYS72D128320HU-5-B	HYB25D512800BE-5B	~ Qimonda (Infineon)		2/23/04	3	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872DDR2N1	K4H510838B-TCCC rev B	Samsung	M381L3313 DTM	2/27/04	3	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C3400 K4-A	MT46V64M8TG(P)-5B rev C	Micron	50-1402-01-B rev B	3/10/04	3	Yes	(64Mx8)*18	
+ATP Electronics	AG28L72T8SHC4M	MT46V64M8TG(P)-5B rev C	Micron	SG184T08L 1 rev 1	4/23/04	3	Yes	(64Mx8)*18	
+TRS	TRS20193	MT46V64M8TG(P)-5B rev C	Micron	M0524LA1 rev 1	5/18/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-E1G/MC	MT46V64M8TG(P)-5B rev C	Micron	UE0532-AA	6/1/04	3	Yes	(64Mx8)*18	
+ATP Electronics	AG28L72T8SHC4S	K4H510838B-TCCC rev B	Samsung	SG184T08L 1 rev 1	6/7/04	3	Yes	(64Mx8)*18	
+Dataram	DTM63682B	MT46V64M8TG(P)-5B rev D	Micron	40024A rev A	6/11/04	3	Yes	(64Mx8)*18	
Buffalo	DD4333-E1GMFJ	MT46V64M8P-5B rev F	Micron	UE0532-AA na	6/23/06	3	Yes	(64Mx8)*18	

**Unbuffered, ECC, DDR400 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Smart Modular Technologies	SG12872DDR2N1SC	K4H510838C-UCCC rev C	Samsung	PG52G184NVBZ6RC B rev A	6/16/06	3	Yes	(64Mx8)*18	
Smart Modular Technologies	SG12872UDR64835SC	K4H510838C-UCCC rev C	Samsung	M381L3313DTM	6/20/06	3	Yes	(64Mx8)*18	
+Legend	L1272DC7-MA6HDH9A	HY5DU12822AT-D43 rev A	Hyundai	BDMA83A6 rev 6	6/17/04	3	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872DDR2N1-I	HYB25D512800BE-5 rev B	~ Qimonda (Infineon)	L-DIM-184-31-1	6/15/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-E1G/SB	K4H510838B-TCCC rev B	Samsung	UE0532-AA	8/17/04	3	Yes	(64Mx8)*18	
+TRS	TRS20177	K4H510838B-TCCC rev B	Samsung	M0524LA1 rev 1	8/19/04	3	Yes	(64Mx8)*18	
Micron	MT18VDDT12872AG-40BD1	MT46V64M8-5B D	Micron		10/6/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-1G/MD	MT46V64M8TG(P)-5B rev D	Micron	UE0532-AA	12/7/04	3	Yes	(64Mx8)*18	
+ATP Electronics	AG28L72T8SHC4S	K4H510838C-UCCC rev C	Samsung	SG184T08L1	1/25/05	3	Yes	(64Mx8)*18	
Samsung	M381L2923BTM-CCC	K4H510838B-TCCC	Samsung		1/27/05	3	Yes	(64Mx8)*18	
+Wintec Industries	3C755681	HYB25D512800BE-5 rev B	~ Qimonda (Infineon)	ZK1024M68 J-A rev A	5/31/05	3	Yes	(64Mx8)*18	
+TRS	TRS20217	HYB25D512800BE-5 rev B	~ Qimonda (Infineon)	M0524LA1 rev 1	7/27/05	3	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C3400 K1-MTD	MT46V64M8TG-5B rev D	Micron	E179889 na	08/11/05	3	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C3400 K1-SAC	K4H510838C-UCCC rev C	Samsung	E179889 na	10/20/05	3	Yes	(64Mx8)*18	
<b>Avant Technology</b>	<b>AVM7228U52C3400 K1-MTF</b>	<b>MT46V64M8TG-5B rev F</b>	<b>Micron</b>	<b>E179889 na</b>	<b>05/01/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*18</b>	
<b>Dataram</b>	<b>DTM63682C</b>	<b>HY5DU12822CTP-D43 rev C</b>	<b>Hynix</b>	<b>40024A rev A</b>	<b>8/11/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*18</b>	

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## *Server Board SE7210TP1-E*

### *Unbuffered, Non-ECC, DDR266 DIMM Modules 1GB Sizes (128Mx72)*

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

### *Unbuffered, Non-ECC, DDR333 DIMM Modules 1GB Sizes (128Mx72)*

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

### *Unbuffered, Non-ECC, DDR400 DIMM Modules 1GB Sizes (128Mx72)*

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD4333-1G/SB	K4H510838B-TCCC rev B	Samsung	UE0532-AA	4/7/04	3	Yes	(64Mx8)*16	
+Buffalo	DD4333-1G/MC	MT46V64M8TG(P)-5B rev C	Micron	UE0532-AA	3/17/04	3	Yes	(64Mx8)*16	
+ATP Electronics	AG28L64T8SHC4S	K4H510838B-TCCC rev B	Samsung	SG184T08L1	4/29/04	3	Yes	(64Mx8)*16	
+Legend	L1264DC7-DE6HDH9A	HY5DU12822AT-D43 rev A	Hyundai	DE640816 A rev 6	5/12/04	3	Yes	(64Mx8)*16	
+Legend	L1264DC7-BU1HDH9A	HY5DU12822AT-D43 rev A	Hyundai	B6U808 rev 1	6/1/04	3	Yes	(64Mx8)*16	
+Buffalo	DD333-1G/SB	K4H510838B-TCB3 rev B	Samsung	UE0532-AA	6/25/04	2.5	Yes	(64Mx8)*16	
+ATP Electronics	AG28L64T8SHC4S	K4H510838C-UCCC rev C	Samsung	SG184T08L1	1/28/05	3	Yes	(64Mx8)*16	
+Buffalo	DD4333-1GSBJ	K4H510838B-UCCC rev B	Samsung	UE0532-AA	5/5/05	3	Yes	(64Mx8)*16	
+Buffalo	DD4333-1G/SC	K4H510838C-UCCC rev C	Samsung	UE0532-AA na	11/1/05	3	Yes	(64Mx8)*16	
+Buffalo	DD4333-1G/MF	MT46V64M8TG-5B rev F	Micron	UE0532-AA na	11/21/05	3	Yes	(64Mx8)*16	
<b>+Buffalo</b>	<b>DD4333-1GMDJ</b>	<b>MT46V64M8P-5B rev D</b>	<b>Micron</b>	<b>UE0532-AA na</b>	<b>3/24/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*16</b>	
<b>Buffalo</b>	<b>DD4333-1GMFJ</b>	<b>MT46V64M8P-5B rev F</b>	<b>Micron</b>	<b>UE0532-AA na</b>	<b>04/29/06</b>	<b>3</b>	<b>Yes</b>	<b>(64Mx8)*16</b>	

*Modules shaded in blue are low profile.*

*Modules in bold text do not contain Lead.*

~ Effective May 1st, 2006, Infineon memory products will be known as Qimonda

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

## Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	<a href="http://www.atpusa.com/">http://www.atpusa.com/</a>	Florence Hsieh Tel 408-732-5831 Fax 408-732-5055 <a href="mailto:sales@atpusa.com">sales@atpusa.com</a>
ATP Electronics -- Taiwan Inc.	<a href="http://www.atpusa.com/">http://www.atpusa.com/</a>	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	<a href="http://www.avanttechnology.com">http://www.avanttechnology.com</a>	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 <a href="mailto:brads@avanttechnology.com">brads@avanttechnology.com</a>
Aved Memory Products	<a href="http://www.avedmemory.com/">http://www.avedmemory.com/</a>	
Buffalo Technology	<a href="http://www.buffalotech.com/">http://www.buffalotech.com/</a>	(800) 967-0959 <a href="mailto:memory@buffalotech.com">memory@buffalotech.com</a>
Centon Electronics	<a href="http://www.centon.com">http://www.centon.com</a>	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	<a href="http://www.corsairmicro.com/">http://www.corsairmicro.com/</a>	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	<a href="http://www.dane-memory.com/">http://www.dane-memory.com/</a>	Michal Hassan @ (949)450-2941 or email @ <a href="mailto:Michal@Dane-memory.com">Michal@Dane-memory.com</a>
Dataram	<a href="http://www.dataram.com/">http://www.dataram.com/</a>	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 <a href="mailto:phenke@dataram.com">phenke@dataram.com</a>
GoldenRAM	<a href="http://www.goldenram.com">http://www.goldenram.com</a>	Jason M. Barrette @ 800-222-861 x7546 <a href="mailto:jasonb@goldenram.com">jasonb@goldenram.com</a> or Michael E. Meyer @800-222-8861 x7512 <a href="mailto:michaelm@goldenram.com">michaelm@goldenram.com</a>
Hitachi	<a href="http://semiconductor.hitachi.com/pointer/">http://semiconductor.hitachi.com/pointer/</a>	
Hyundai/Hynix Semiconductor	<a href="http://www.hea.com/">http://www.hea.com/</a>	
~ Qimonda (Infineon)	<a href="http://www.infineon.com/business/distribut/index.htm">http://www.infineon.com/business/distribut/index.htm</a>	
ITAUCOM	<a href="http://www.itaucum.com.br">http://www.itaucum.com.br</a>	
JITCO CO LTD	<a href="http://www.jitco.net/">http://www.jitco.net/</a>	Seong Jeon Tel: 82-32-817-9740 <a href="mailto:s.jeon@jitco.net">s.jeon@jitco.net</a>
Kingston	<a href="http://www.kingston.com">http://www.kingston.com</a>	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	<a href="http://www.legacyelectronics.com">http://www.legacyelectronics.com</a>	U.S. Contact: Keri Albers 888 466 3853 ext. 307 European Contact: 49 89 370 664 11
Legend	<a href="http://www.legend.com.au">http://www.legend.com.au</a>	
Micron	<a href="http://silicon.micron.com/mktg/">http://silicon.micron.com/mktg/</a> <a href="http://silicon.micron.com/mktg/mbqual/qual_data.cfm">http://silicon.micron.com/mktg/mbqual/qual_data.cfm</a>	
MSC Vertriebs GmbH	<a href="http://www.msc-ge.com">http://www.msc-ge.com</a>	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 <a href="mailto:wpe@msc-ge.com">wpe@msc-ge.com</a>
Netlist, Inc	<a href="http://www.netlistinc.com">http://www.netlistinc.com</a>	Christopher Lopes 949.435.0025 tel 949.435.0031 fax <a href="mailto:sales@netlistinc.com">sales@netlistinc.com</a>

<b>Vendor Name</b>	<b>Web URL</b>	<b>Vendor Direct Sales Info</b>
<b>Peripheral Enhancements</b>	<a href="http://www.peripheral.com/">http://www.peripheral.com/</a>	
<b>PNY</b>	<a href="http://www.pny.com/internet_explorer/LPB.HTML">http://www.pny.com/internet_explorer/LPB.HTML</a>	
<b>Samsung</b>	<a href="http://www.korea.samsungsemi.com/locate/buy/list_na.html">http://www.korea.samsungsemi.com/locate/buy/list_na.html</a>	For US customers go to: <a href="http://www.mymemorystore.com/">http://www.mymemorystore.com/</a>
<b>Silicon Tech</b>	<a href="http://www.silicontech.com/contact/salescontacts.shtml">http://www.silicontech.com/contact/salescontacts.shtml</a>	
<b>Simple Tech</b>	<a href="http://www.simpletech.com">http://www.simpletech.com</a>	Ron Darwish @ (949) 260-8230 or email @ <a href="mailto:Rdarwish@Simpletech.com">Rdarwish@Simpletech.com</a>
<b>SMART Modular Technologies</b>	<a href="http://www.smartm.com/channel">http://www.smartm.com/channel</a>	Gene Patino (949) 439-6167 <a href="mailto:Gene.Patino@Smartm.com">Gene.Patino@Smartm.com</a>
<b>Swissbit</b>	<a href="http://www.swissbit.com">http://www.swissbit.com</a>	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 <a href="mailto:tony.cerreta@swissbitna.com">tony.cerreta@swissbitna.com</a>
<b>TechnoLinc Corporation</b>	<a href="http://www.technolinc.com">http://www.technolinc.com</a>	David Curtis 510-445-7400 <a href="mailto:davidc@technolinc.com">davidc@technolinc.com</a>
<b>TRS* Tele-Radio-Space GmbH</b>	<a href="http://www.certified-memory.com">http://www.certified-memory.com</a> <a href="http://www.certified-memory.de">http://www.certified-memory.de</a>	Vender Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 <a href="mailto:Andreas.gruendl@trs-eu.com">Andreas.gruendl@trs-eu.com</a>
<b>Unigen</b>	<a href="http://www.unigen.com">http://www.unigen.com</a>	
<b>Ventura Technology Inc</b>	<a href="http://www.venturatech.com">http://www.venturatech.com</a>	Sam Lewis 760 599-0080 ext. 1
<b>Viking InterWorks</b>	<a href="http://www.vikinginterworks.com">http://www.vikinginterworks.com</a>	
<b>Virtium Technology Inc</b>	<a href="http://www.virtium.com">http://www.virtium.com</a>	Tod Skelton @ (949) 460-0020 ext. 146 or email @ <a href="mailto:tod.skelton@virtium.com">tod.skelton@virtium.com</a>
<b>Legend</b>	<a href="http://www.legend.com.au">http://www.legend.com.au</a>	Tel: 800-338-2361 Fax: 949-459-8577 <a href="mailto:orderdesk@vikingcomponents.com">orderdesk@vikingcomponents.com</a>
<b>Wintec Industries</b>	<a href="http://www.wintecindustries.com">http://www.wintecindustries.com</a>	Tel 510-360-6300 Fax 510-770-9338

### **CMTL\* (Computer Memory Test Labs)**

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

#### IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with boxed processors. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the boxed processor baseboard. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server Board product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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